



Semiconductor Device Type:			T4X			TQFP-44-10x10x1mm-MatteTin			Package Homogeneous Materials			
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	218.09	(mg) Total	Mold Compound	% of Total Weight	79.80		
Silica, vitreous	60676-86-0	Mold Compound	67.83	185.38	678296		Silica, vitreous	60676-86-0	85.00			
Epoxy Resin	Trade Secret	Mold Compound	6.94	18.97	69425		Epoxy Resin	Trade Secret	8.70			
Phenolic Resin	Trade Secret	Mold Compound	4.79	13.09	47881		Phenolic Resin	Trade Secret	6.00			
Carbon Black	1333-86-4	Mold Compound	0.24	0.65	2393		Carbon Black	1333-86-4	0.30			
Copper	7440-50-8	Lead Frame	10.00	27.33	100003		Total			100.00		
Nickel	7440-02-0	Lead Frame	0.27	0.73	2667							
Silver	7440-22-4	Lead Frame	0.18	0.48	1753	28.70	(mg) Total	Lead Frame	% of Total Weight	10.50		
Silicon	7440-21-3	Lead Frame	0.05	0.13	472		Copper	7440-50-8	95.24			
Magnesium	7439-95-4	Lead Frame	0.01	0.03	106		Nickel	7440-02-0	2.54			
Silver	7440-22-4	Die Attach	0.60	1.64	6001		Silver	7440-22-4	1.67			
Acrylate Urethane Oligomer	Trade Secret	Die Attach	0.15	0.41	1500		Silicon	7440-21-3	0.45			
Silicon	7440-21-3	Die	7.50	20.50	75002		Magnesium	7439-95-4	0.10			
Copper	7440-50-8	Wire Bond	0.20	0.54	1958		Total			100.00		
Palladium	2023568	Wire Bond	0.00	0.01	40							
Gold	7440-57-5	Wire Bond	0.00	0.00	4	2.05	(mg) Total	Die Attach	% of Total Weight	0.75		
Tin	7440-31-5	Lead Plating	1.25	3.42	12499		Silver	7440-22-4	80.00			
TOTALS:			100.00	273.30	1,000,000		Acrylate Urethane Oligomer	Trade Secret	20.00			
273.30 mg Total Mass							Total			100.00		
						20.50	(mg) Total	Die	% of Total Weight	7.50		
							Silicon	7440-21-3	100.00			
							Total			100.00		
						0.55	(mg) Total	Wire Bond	% of Total Weight	0.20		
							Copper	7440-50-8	97.81			
							Palladium	2023568	2.01			
							Gold	7440-57-5	0.18			
							Total			100.00		
						3.42	(mg) Total	Lead Plating	% of Total Weight	1.25		
							Tin	7440-31-5	100.00			
							Total			100.00		

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